

L Number	Hits	Search Text	DB	Time stamp
-	89	(73/504.04).CCLS.	USPAT; US-PGPUB	2002/09/12 17:15
-	300	(73/504.12).CCLS.	USPAT; US-PGPUB	2002/09/10 17:41
-	27	((73/504.12).CCLS.) and resin	USPAT; US-PGPUB	2002/09/10 17:43
-	512	73/514.32	USPAT; US-PGPUB	2002/09/12 18:19
-	270	73/514.01	USPAT; US-PGPUB	2002/09/12 17:22
-	23	73/514.32 and integrated near2 chip	USPAT; US-PGPUB	2002/09/12 18:24
-	4	(73/514.32 and integrated near2 chip) and resin	USPAT; US-PGPUB	2002/09/12 18:22
-	13	73/514.01 and integrated near2 chip	USPAT; US-PGPUB	2002/09/12 18:25
-	2	(73/514.01 and integrated near2 chip) and resin	USPAT; US-PGPUB	2002/09/12 18:26
-	43539	thermoplastic near2 resin	USPAT; US-PGPUB	2002/09/12 18:27
-	24	(thermoplastic near2 resin) and acceleration near2 sensor	USPAT; US-PGPUB	2002/09/13 09:50
-	9	(thermoplastic near2 resin) and gyro	USPAT; US-PGPUB	2002/09/13 10:09
-	15	(thermosetting near2 resin) and gyro	USPAT; US-PGPUB	2002/09/13 10:21
-	33806	semiconductor near2 chip	USPAT; US-PGPUB	2002/09/13 10:22
-	304	semiconductor near2 sensor near2 chip	USPAT; US-PGPUB	2002/09/13 10:22
-	262	(semiconductor near2 chip) and (semiconductor near2 sensor near2 chip)	USPAT; US-PGPUB	2002/09/13 10:24
-	52	((semiconductor near2 chip) and (semiconductor near2 sensor near2 chip)) and acceleration	USPAT; US-PGPUB	2002/09/13 10:47
-	5	((semiconductor near2 chip) and (semiconductor near2 sensor near2 chip)) and acceleration) and thermoplastic	USPAT; US-PGPUB	2002/09/13 11:27
-	5	((semiconductor near2 chip) and (semiconductor near2 sensor near2 chip)) and acceleration) and thermoplastic) and acceleration	USPAT; US-PGPUB	2002/09/13 11:28